

# WEST Search History

DATE: Wednesday, March 05, 2003

| <u>Set Name</u>   | <u>Query</u>  | <u>Hit Count</u> | <u>Set Name</u> |
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| side by side  |   | result set       |                 |
| <i>DB=USPT,PGPB,JPAB,EPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i> |   |                  |                 |
| L16   | L14 and target near (cu or copper)  | 13               | L16             |
| L15   | L14 and target near (al or aluminum)  | 32               | L15             |
| L14   | l3 and temperature  | 245              | L14             |
| L13   | l3 and (anneal or annealed or annealing)  | 37               | L13             |
| L12   | L11 and target near (cu or copper)  | 0                | L12             |
| L11   | l4 and friction and target near (al or aluminum or cu or copper or ti or titanium or steel or stainless steel)  | 8                | L11             |
| L10   | l3 and target near (al or aluminum or cu or copper or ti or titanium or co or cobalt)   | 64               | L10             |
| L9  | l4 and friction and target near (al or aluminum or cu or copper or ti or titanium or co or cobalt)  | 8                | L9              |
| L8  | l4 and (weld or welding) near (tig or tungsten inert)   | 5                | L8              |
| L7  | l4 and (weld or welding) near (friction or stir)  | 9                | L7              |
| L6  | l3 and (filler or foil or insert or intermediate or intermediary or layer or interlayer)  | 246              | L6              |
| L5  | L4 and (weld or welding) near (e beam or electron beam or laser)  | 17               | L5              |
| L4  | L3 and (weld or welding)  | 86               | L4              |
| L3  | L1 and (press or pressure or pressing or pressed or force or load or hip or diffusion (bond or bonded or bonding))  | 294              | L3              |
| L2  | L1 and (press or pressure or pressing or pressed or force or load or hip)   | 292              | L2              |
| L1  | target and backing plate and (join or joining or bond or bonding or solder or soldering or braze or brazing or weld or welding) and (mate or mating or salient or groove or rough or grooved or roughened or interlock or interlocking or knurl or knurled or notch or notched) | 329              | L1              |

END OF SEARCH HISTORY

## WEST

 Generate Collection

L6: Entry 1 of 2

File: JPAB

Dec 27, 1984

PUB-N0: JP359232270A  
DOCUMENT-IDENTIFIER: JP 59232270 A  
TITLE: SPUTTERING TARGET

PUBN-DATE: December 27, 1984

## INVENTOR-INFORMATION:

| NAME                | COUNTRY |
|---------------------|---------|
| MATSUOKA, TOMIZO    |         |
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## ASSIGNEE-INFORMATION:

| NAME                           | COUNTRY |
|--------------------------------|---------|
| MATSUSHITA ELECTRIC IND CO LTD |         |

APPL-NO: JP58106460

APPL-DATE: June 14, 1983

US-CL-CURRENT: 445/58

INT-CL (IPC): C23C 15/00; H01L 21/31

## ABSTRACT:

PURPOSE: To provide a titled target which prevents breakage and peeling from an electrode owing to thermal impact even if the power thereof is large by providing grooves having a sectional shape of a lancing type or the like for joining the electrode side of the sputtering target plate and embedding a low melting metal therein.

CONSTITUTION: Grooves 4' having a sectional shape of a lancing type are provided on the surface of a sputtering target plate 3' consisting of a metal or ceramics which contact with the cathode electrode 1' side and a low melting metal is embedded in said grooves. The target 3' thereof is adhered and fixed by indium low melting solder 2' onto the metallic cathode electrode 1'. The target constructed in the above-mentioned way has the increased mechanical joint strength between the target plate 3' and the electrode 1 and is free from crazing, peeling, etc. even if the sputtering power is large. A high deposition rate is thus obtd. The adhesive strength is further improved by constituting the section of said grooves 4' in wedge-shape or oblique with respect to the plane of the plate 3'.

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